

FEATURES

Low Reverse Leakage

| High Forward Surge Capability

High Reliability

High Temperature Soldering Guaranteed:260°C/10seconds



MECHANICAL DATA

Case:SMA Molded Plastic	
Epoxy: Ul 94v-0 Rate Flame Retardant	
Lead: Pure Tin Plated. Lead Free	

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

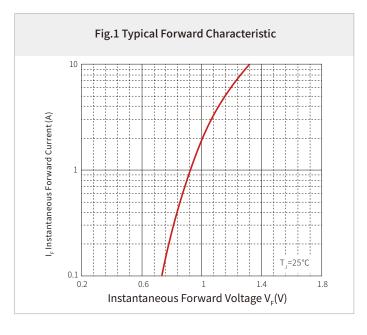
MAXIMUM RATINGS AND CHARACTERISTICS ($T_A = 25$ °C)

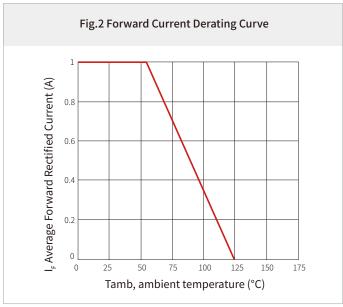
Symbol	Parameter		М1	M2	М3	M4	M5	М6	М7	Unit
	Marking		M1	M2	М3	M4	M5	М6	М7	
V_{RRM}	Maximum repetitive peak reverse vo	oltage	50	100	200	400	600	800	1000	
V _{RMS}	Maximum RMS voltage		35	70	140	280	420	560	700	V
V _{DC}	Maximum DC blocking voltage		50	100	200	400	600	800	1000	-
I _{F(AV)}	Maximum average forward rectified current					1.0				
I _{FSM}	Non-repetitive peak forward surge current 8.3 ms singlehalf sine-wave			30					А	
V _F	Maximum forward voltage I _F =1A					1.1				V
ı	Maximum reverse current $@V_{DC}$ $T_A=25^{\circ}C$					5				
I _R						100				μА
R _{eJA}	Typical thermal resistance (Note 1)					47				°C/W
CJ	Type junction capacitance V _R =4.0V,f=1MHz			65					PF	
T _J	Operating junction temperature rang			-55~+125					°C	
T _{STG}	Storage temperature rang				-	55~+15()			°C

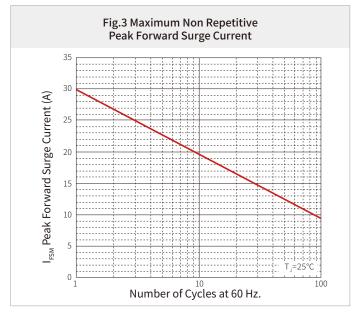
Note: 1) Thermal resistance from junction to ambient, PCB mounted.

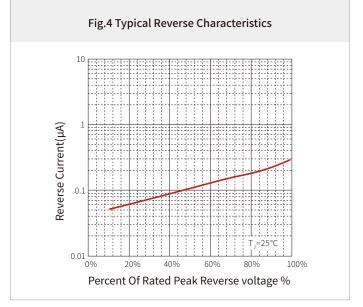


CHARACTERISTIC CURVES





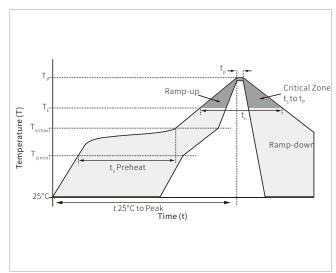




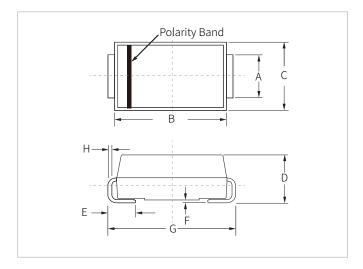


SOLDERING PARAMETERS

	Lead-free assembly			
	Temperature Max (T _{s(min)})	150°C		
Pre Heat	Temperature Max (T _{s(max)})	200°C		
	Time (min to max) (t _s)	60 – 180 secs		
Average ran	Average ramp up rate (Liquidus Temp (T _L) to peak			
	T _{S(max)} to T _L - Ramp-up Rate			
Reflow	Temperature (T _L) (Liquidus)	217°C		
Reliow	Time (min to max) (t _L)	60 – 150 seconds		
Peak Temp	260°C			
Time within	20 – 40 seconds			
Ramp-dow	6°C/second max			
Time 25°C t	8 minutes max.			
Do not exce	260°C			



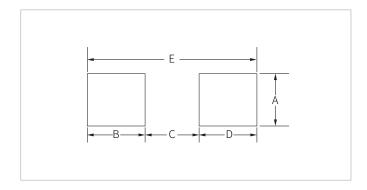
DO-214AC(SMA) PACKAGE INFORMATION



Ref.	Millimeters		Inches		
ivei.	Min.	Max.	Min.	Max.	
А	1.20	1.60	0.047	0.063	
В	4.20	4.60	0.165	0.181	
С	2.40	2.80	0.094	0.110	
D	2.00	2.40	0.079	0.094	
Е	0.76	1.52	0.030	0.060	
F	0.02	0.20	0.001	0.008	
G	4.85	5.25	0.191	0.207	
Н	0.15	0.30	0.006	0.012	



RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches		
KCI.	Min.	Max.	Min.	Мах.	
А	1.63	-	0.064	-	
В	1.45	-	0.057	-	
С	-	2.80	-	0.090	
D	1.45	-	0.057	-	
E	5.28REF		0.20	8REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
M1~M7	DO-214AC(SMA)	7500PCS	13"



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By QR Code





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Machat

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